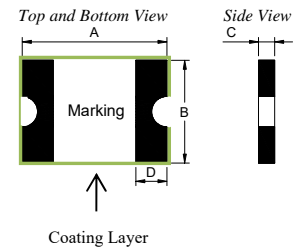


1、 Physical Dimensions(size of 1206)

Unit:mm

Part Number	A*		B*		C		D	Marking
	Min	Max	Min	Max	Min	Max	Min	
KNSML300TC	3.00	3.70	1.50	2.20	0.40	0.80	0.25	TF

* Dimension is measured after coating



2、 Electrical Characteristics

● V_{max}= 6Vdc ● I_{max}= 50A

Model	Hold current and Trip current (AMPS)				Time To Trip (Sec.)		Pd _{typ} (W)	R _{min} (Ω)	R _{lmax} (Ω)
	25°C		60°C		8A @ 25°C		25°C,6V	25°C	25°C
KNSML300TC	I-hold	I-trip	I-hold	I-trip	Min	Max	Max	0.003	0.020
	3.00	6.00	2.00	4.00	-	5.0	1.20		

I-hold: Holding Current: maximum current at which the device will not trip in 25°C or 60°C still air.

I-trip: Tripping Current minimum current at which the device will trip in 25°C or 60°C still air.

V_{max}: Maximum voltage device can withstand without damage at rated current.

I_{max}: Maximum fault current device can withstand without damage at rated voltage.

Time To Trip: Maximum time to trip(s) at assigned current.

Pd_{typ}: Rated working power.

R_{min}: Minimum resistance of device prior to trip at 25°C.

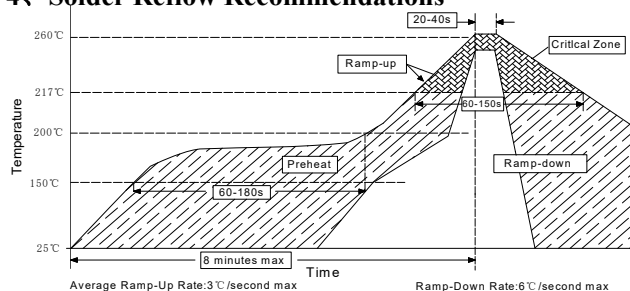
R_{lmax}: Maximum resistance of device is measured one hours post reflow at 25°C.

Noted: All electrical function test is conducted after PCB mounted.

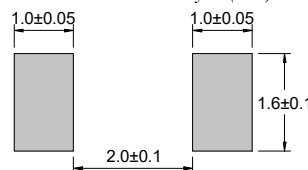
3、 Thermal Derating

KNSML300TC	Maximum ambient operating temperature								
	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C
Hold Current(A)	4.50	3.90	3.45	3.00	2.55	2.25	2.00	1.65	1.20
Trip Current(A)	9.00	7.80	6.91	6.00	5.11	4.51	4.00	3.31	2.40

4、 Solder Reflow Recommendations



Recommended Pad Layout(mm)



Notes: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

5、 Package Information

Packing quantity: 4000PCS/Reel

Note: Reel packaging per EIA-481-1 standard